Assembly Transfer of Small Body Punched LFCSP Products to Amkor Philippines AP1

Qualification Plan Summary of 4x4mm and 5x5mm Hidden Paddle Punched LFCSP at Amkor Philippines

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	January 2016
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 77	January 2016
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	January 2016
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	1 x 77	January 2016
Electrostatic Discharge *Field Induced Charge Device Model*	JEDEC *JESD22-C101*	3/voltage	January 2016

*Preconditioned per JEDEC/IPC J-STD-020

Qualification Results Summary of 4x4mm and 5x5mm Punched LFCSP at Amkor Philippines

QUALIFICATION PLAN

TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	1 x 77	PASS
Electrostatic Discharge *Field Induced Charge Device Model*	JEDEC *JESD22-C101*	3/voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020